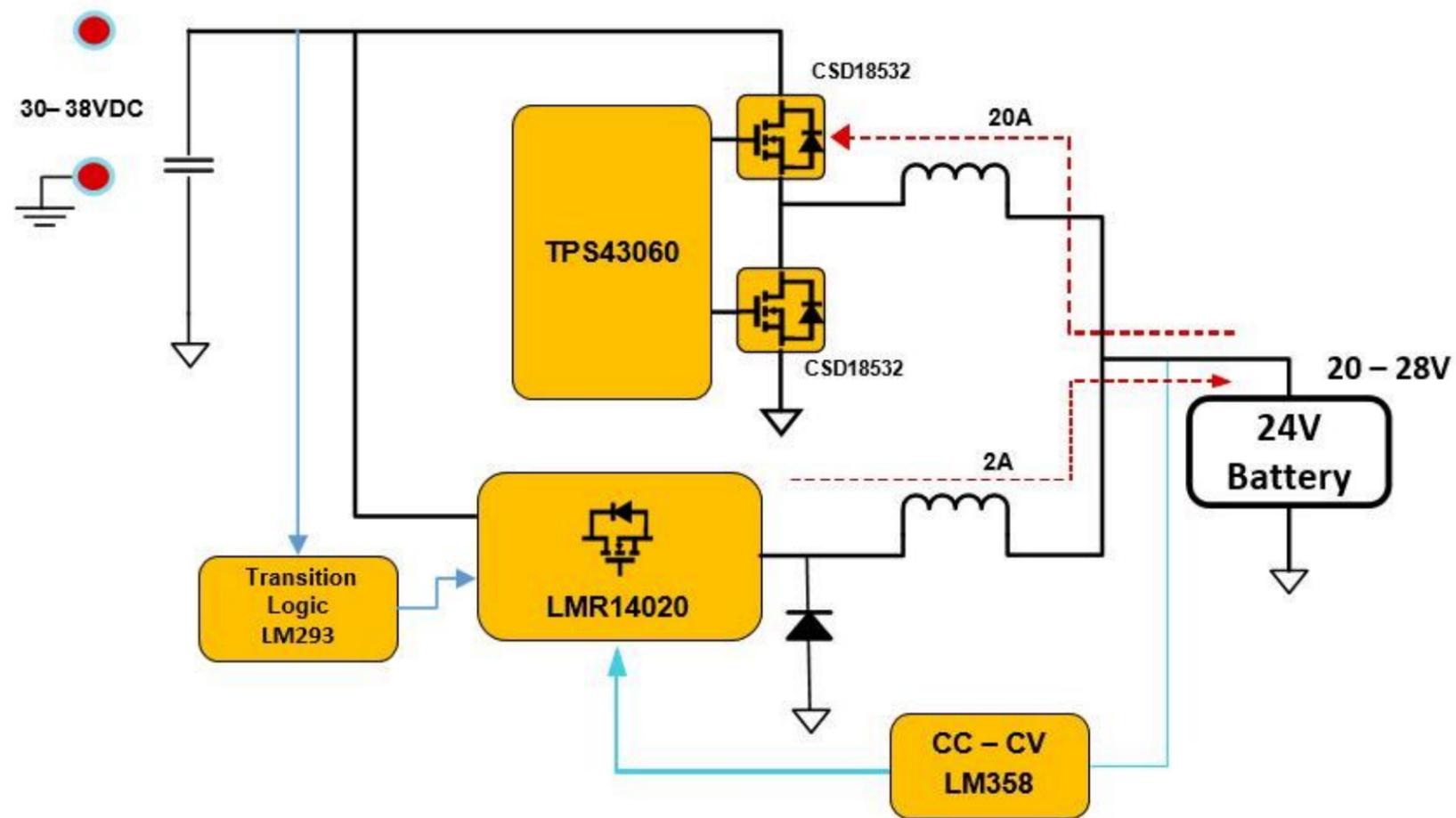


| Revision History | | | | |
|------------------|-------|---------------|-------------|-------|
| Rev | ECN # | Approved Date | Approved by | Notes |
| N/A | N/A | N/A | N/A | N/A |

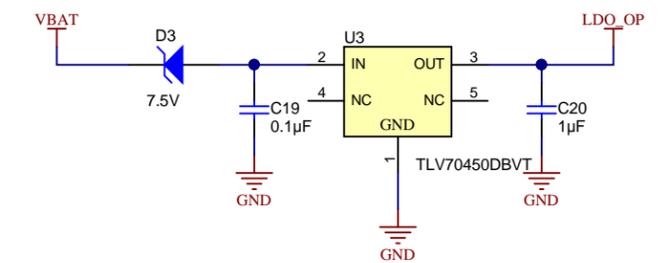
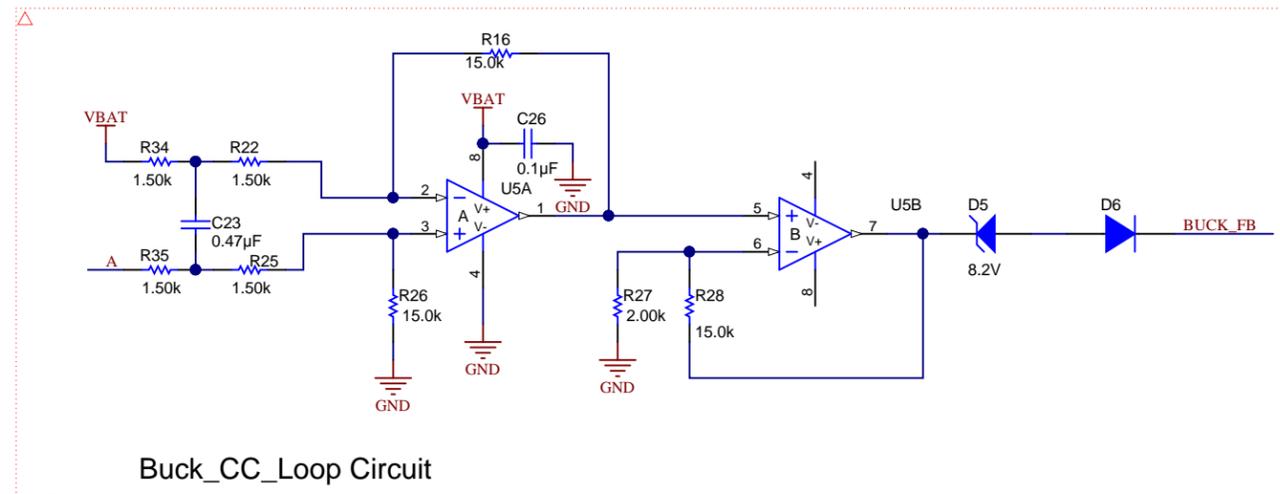
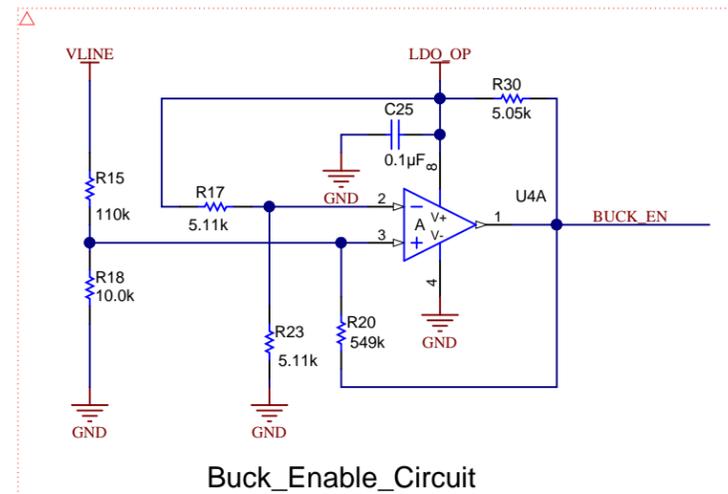
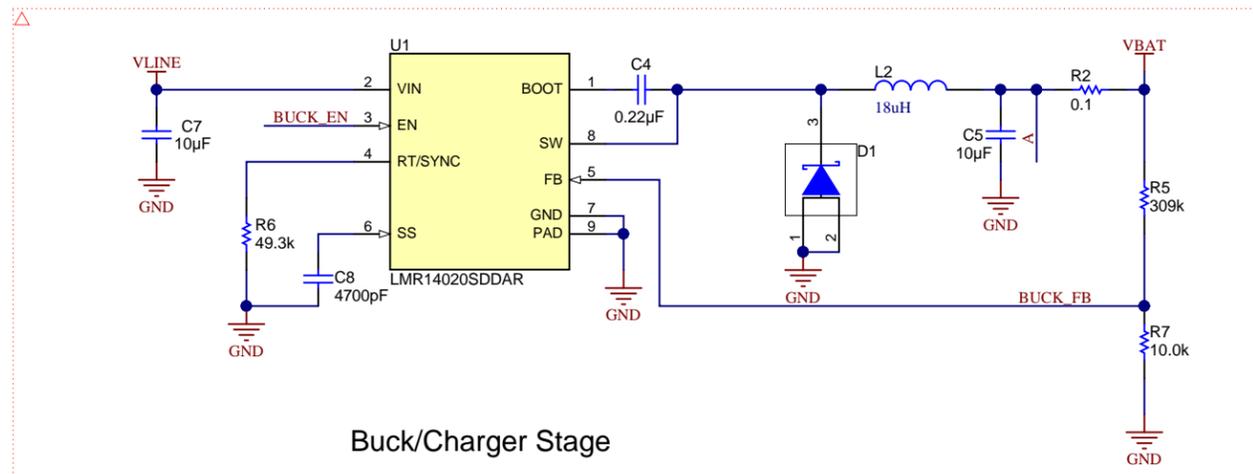
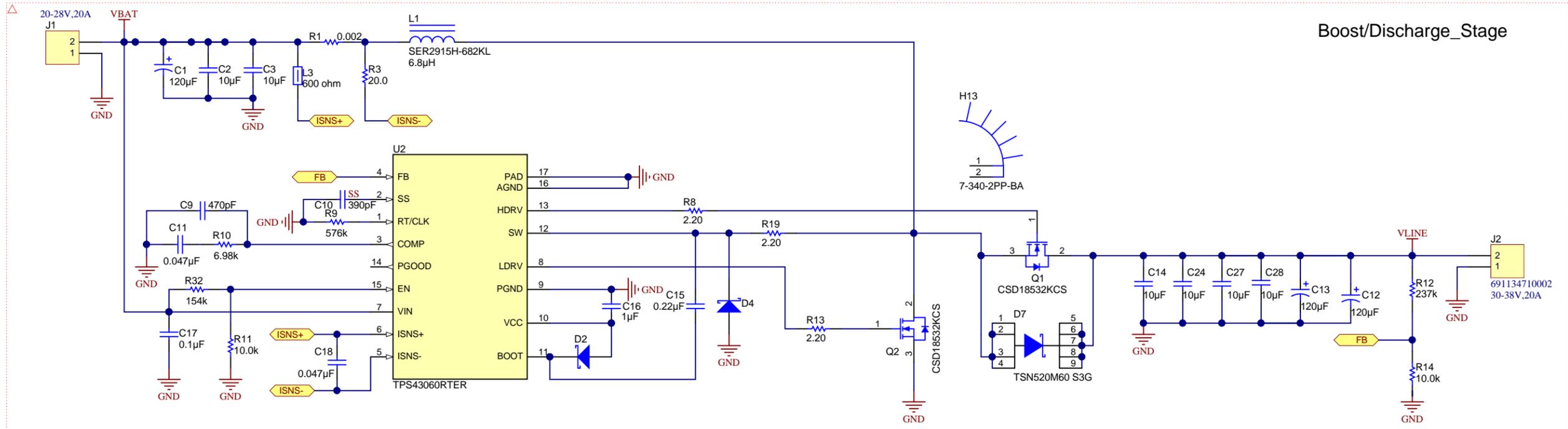


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|-----------------------------------|--|--------------------------|
| Orderable: N/A | Designed for: Public Release | Mod. Date: 12/13/2017 |
| TID #: TIDA-01558 | Project Title: 500W Buck Boost | |
| Number: TIDA-01558 | Rev: E1 | Sheet Title: Cover Sheet |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 1 of 3 |
| Drawn By: Neha Nain | File: TIDA-01558_CoverSheet_SchDoc | Size: B |
| Engineer: Neha Nain | Contact: http://www.ti.com/support | |



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| Orderable: N/A | Designed for: Public Release | Mod. Date: 12/13/2017 |
| TID #: TIDA-01558 | Project Title: 500W Buck Boost | |
| Number: TIDA-01558 | Rev: E1 | Sheet Title: Sheet1 |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 2 of 3 |
| Drawn By: Neha Nain | File: TIDA-01558_Sheet1.SchDoc | Size: B |
| Engineer: Neha Nain | Contact: http://www.ti.com/support | |



PCB Number: TIDA-01558
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
Logo3

PCB LOGO
Logo4

PCB LOGO
Logo5



LOGO6

| Label Table | |
|-------------|------------|
| Variant | Label Text |
| 001 | ChangeMe! |
| 002 | ChangeMe! |
| | |
| | |
| | |
| | |
| | |

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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| TID #: TIDA-01558 | Project Title: 500W Buck Boost | | |
| Number: TIDA-01558 | Rev: E1 | Sheet Title: Hardware | |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 3 of 3 | |
| Drawn By: Neha Nain | File: TIDA-01558_Hardware.SchDoc | Size: B | |
| Engineer: Neha Nain | Contact: http://www.ti.com/support | | |

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